

SOT1514-2

LFBGA404, plastic, low profile fine-pitch ball grid array; 404 balls; 0.65 mm pitch; 17 mm x 17 mm x 1.32 mm body

16 May 2018

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA404
Package type industry code	LFBGA404
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Mounting method type	S (surface mount)
Issue date	15-3-2018
Manufacturer package code	98ASA01201D

Table 1. Package summary

Parameter		Min	Typ	Nom	Max	Unit
package length		-	-	17	-	mm
package width		-	-	17	-	mm
seated height		-	-	1.32	-	mm
nominal pitch		-	-	0.65	-	mm
actual quantity of termination		-	-	404	-	A/A



2. Package outline

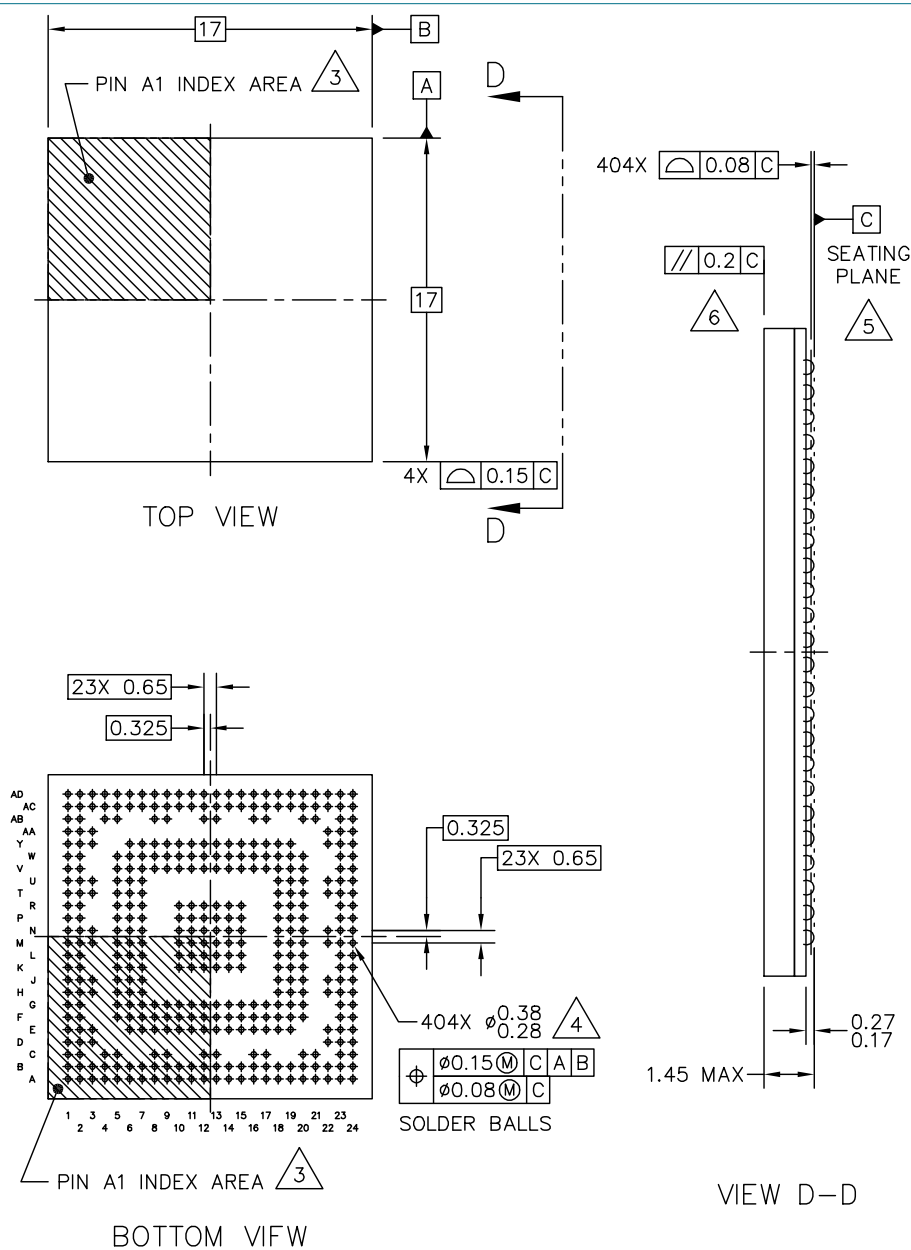


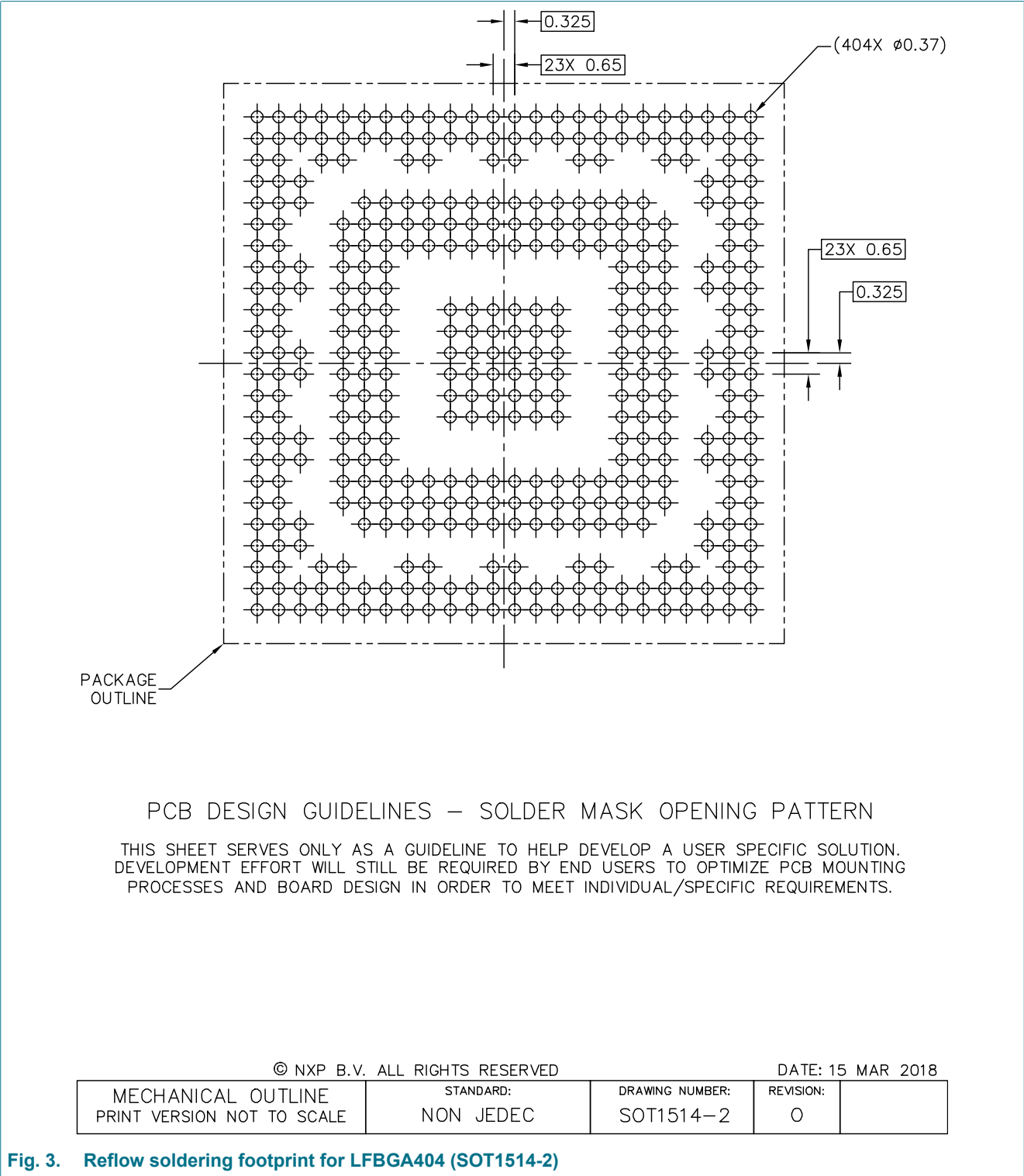
Fig. 1. Package outline LFBGA404 (SOT1514-2)

- NOTES:
- 1. ALL DIMENSIONS IN MILLIMETERS.
 - 2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M–1994.
 - 3. PIN A1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
 - 4. MAXIMUM SOLDER BALL DIAMETER MEASURED PARALLEL TO DATUM C.
 - 5. DATUM C, THE SEATING PLANE, IS DETERMINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
 - 6. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

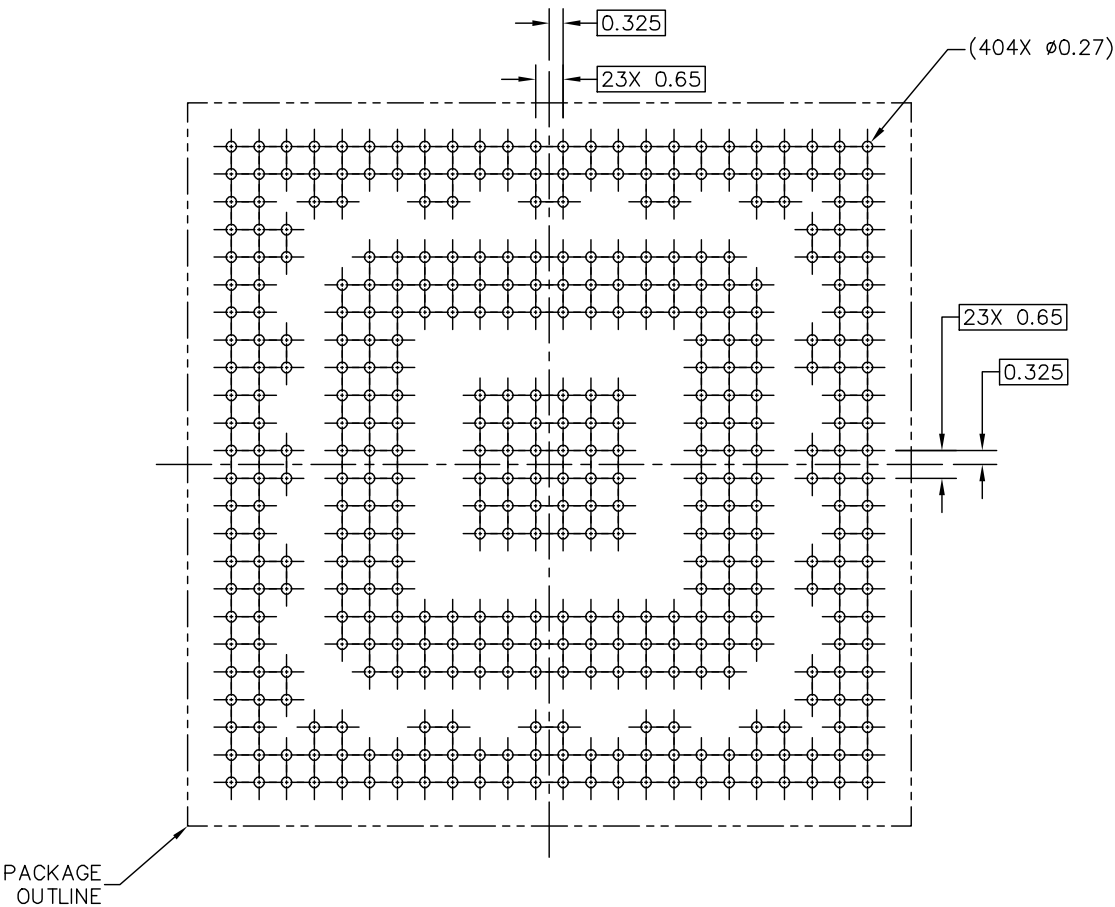
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MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: SOT1514–2	REVISION: 0	

Fig. 2. Package outline note LFBGA404 (SOT1514-2)

3. Soldering



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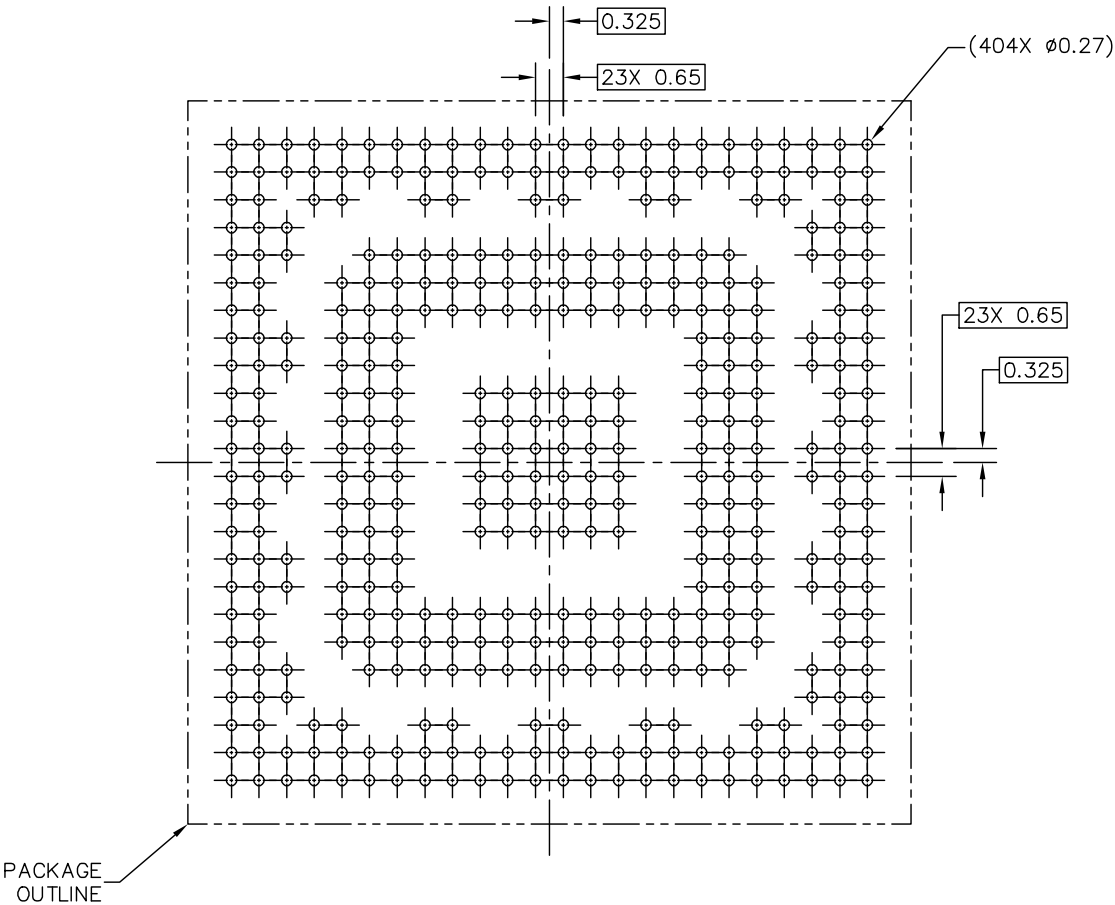


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Fig. 4. Reflow soldering footprint part2 for LFBGA404 (SOT1514-2)



RECOMMENDED STENCIL THICKNESS 0.1

PCB DESIGN GUIDELINES – SOLDER PASTE STENCIL

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Fig. 5. Reflow soldering footprint part3 for LFBGA404 (SOT1514-2)

4. Legal information

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